- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$
- **High-Impedance State During Power Up** and Power Down
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OI})
- **Package Options Include Plastic** Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

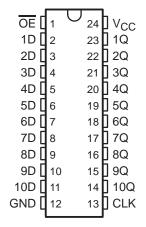
description

These 10-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

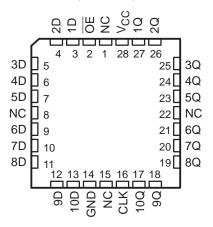
The ten flip-flops are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the devices provide true data at the Q outputs.

A buffered output-enable (\overline{OE}) input can be used to place the ten outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

SN54ABT821 . . . JT OR W PACKAGE SN74ABT821A . . . DB. DW. OR NT PACKAGE (TOP VIEW)



SN54ABT821 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

OE does not affect the internal operations of the latch. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT821 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT821A is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

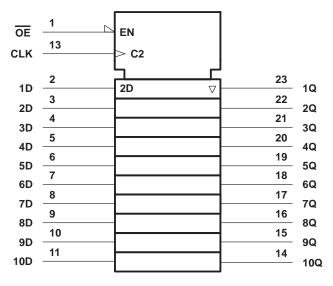
EPIC-IIB is a trademark of Texas Instruments Incorporated



FUNCTION TABLE (each flip-flop)

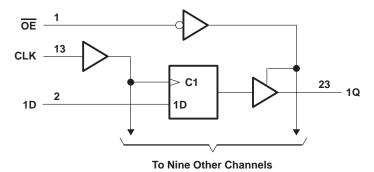
	INPUTS		OUTPUT
OE	CLK	D	Q
L	1	Н	Н
L	\uparrow	L	L
L	H or L	Χ	Q ₀
Н	X	Χ	Z

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, and W packages.



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, I _O : SN54ABT821	96 mA
SN74ABT821A	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DB package	104°C/W
DW package	81°C/W
NT package	67°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT821		SN74ABT821A		UNIT
		MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	V
loн	High-level output current		-24		-32	mA
loL	Low-level output current		48		64	mA
Δt/Δν	Input transition rise or fall rate		10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate	200		200		μs/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.



SN54ABT821, SN74ABT821A 10-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCBS193E - FEBRUARY 1991 - REVISED MAY 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Т	A = 25°C	;	SN54ABT821		SN74ABT821A		UNIT
PARAMETER	IEST COND	IIIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNII
VIK	V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\/a	$V_{CC} = 5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		I _{OH} = -24 mA	2			2				
	V _{CC} = 4.5 V	I _{OH} = -32 mA	2*					2		
V ₂ .	V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V
VOL		I _{OL} = 64 mA			0.55*				0.55	V
V _{hys}				100						mV
lį	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	$V_I = V_{CC}$ or GND			±1		±1		±1	μΑ
I _{OZPU} ‡	$V_{CC} = 0$ to 2.1 V, $V_{O} = 0.5$ to 2.7 V, $\overline{OE} = X$				±50*				±50	μΑ
I _{OZPD} ‡	$V_{CC} = 2.1 \text{ V to } 0, V_{O} = 0.5 \text{ to } 2.7 \text{ V}, \overline{OE} = X$				±50*				±50	μΑ
IOZH	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, V_{O} = 2.7 \text{ V}, \overline{OE} \ge 2 \text{ V}$				10		10		10	μΑ
lozL	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V, V}_{O} =$	0.5 V, OE ≥ 2 V			-10		-10		-10	μΑ
l _{off}	$V_{CC} = 0$,	V _I or V _O ≤ 4.5 V			±100				±100	μΑ
ICEX	V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ
IO§	V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
		Outputs high		1	250		250		250	μΑ
ICC	$V_{CC} = 5.5 \text{ V, I}_{O} = 0,$ $V_{I} = V_{CC} \text{ or GND}$	Outputs low		24	38		38		38	mA
	Al = ACC of GIAD	Outputs disabled		0.5	250		250		250	μΑ
ΔICC¶	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				1.5		1.5		1.5	mA
C _i	V _I = 2.5 V or 0.5 V	·		3.5						pF
Co	V _O = 2.5 V or 0.5 V			7.5						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V _{CC} = 5 V, T _A = 25°C		SN54ABT821		SN74ABT821A		UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX		
fclock	Clock frequency		0	125	0	125	0	125	MHz
	Pulse duration, CLK high or low	High	2.9		2.9		2.9		no
t _W	Fulse duration, CLK high of low	Low	3.8		3.8		3.8		ns
t _{SU} Setup time, data before CLK↑		2.1		2.1		2.1		ns	
t _h	Hold time, data after CLK↑		1.3		1.3		1.3		ns



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] This parameter is characterized, but not production tested.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V 4 = 25°C	/, ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
fmax			125			125		MHz
^t PLH	CLK	Q	1.6†	4.1	5.6	1.6†	6.9	ns
^t PHL		α	2.1†	4.6	6.2	2.1†	6.9	115
^t PZH	ŌĒ	Q	1	3	4.5	1	6	ns
t _{PZL}	OE	ά	2.2	4.1	5.6	2.2	6.5	115
^t PHZ	ŌĒ	Q	2.7	4.7	6.2	2.7	7	ns
t _{PLZ}	UE UE	ζ	1.7†	4.6	6.1	1.7 [†]	7	115

[†]This data sheet limit may vary among suppliers.

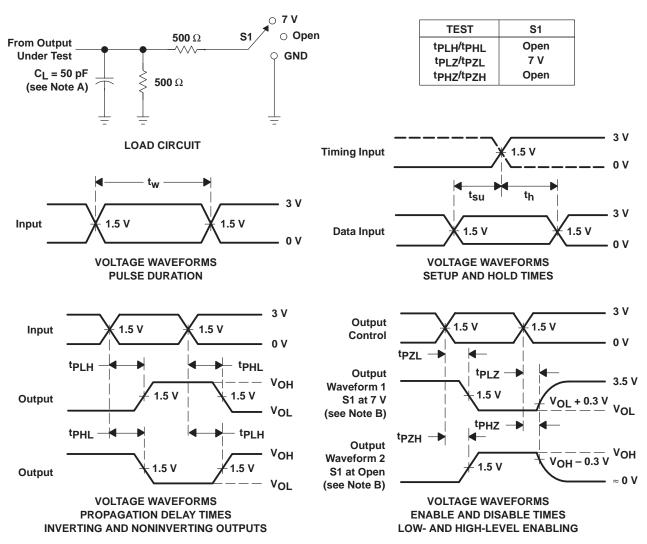
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

		TO (OUTPUT)						
PARAMETER	FROM (INPUT)		V ₍	CC = 5 V 4 = 25°C	/, ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
f _{max}			125			125		MHz
t _{PLH}	CLK	Q	1.6†	4.1	5.6	1.6†	6.2	ns
t _{PHL}		Q	2.3†	4.6	6.2	2.3†	6.7	110
^t PZH	ŌĒ	Q	1	3	4.5	1	5.8	ns
^t PZL	OE	ά	2.2	4.1	5.6	2.2	6.3	110
^t PHZ	ŌĒ	Q	2.7	4.7	6.2	2.7	6.7	ns
t _{PLZ}	UE UE	ζ	1.7†	4.6	6.1	1.7	6.5	115

[†] This data sheet limit may vary among suppliers.



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{f} \leq 2.5 \text{ ns.}$
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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